	11:4-	Sear h Text	DB	Time stamp
-	Hits	Jeal II leat		
lumber	1239	438/690,691,692.ccls.	USPAT	2002/06/17
1	1239	430/030,031,032.0013.		12:18
	074	438/623,624.ccls.	USPAT	2002/06/17
2	971	438/023,024.0015.		12:19
		400/000 -	USPAT	2002/06/17
3	295	438/626.ccls.		12:19
		100 T 1 T 10 - 10	USPAT	2002/06/17
4	248	438/715,716.ccls.	00.71	12:19
			USPAT;	2002/06/17
5	1	leong-lup\$.in.	US-PGPUB;	12:19
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
			USPAT	2002/06/17
6	23600	planar\$8 and heat\$3 and pressure and	JOFAI	12:26
		mechan\$4 and (layer film wafer substrate)	USPAT	2002/06/17
7	5156	(planar\$8 and heat\$3 and pressure and	USPAI	12:24
		mechan\$4 and (layer film wafer substrate))		12:24
		and (planar\$8 same heat\$3)		2002/06/17
8	3442	((planar\$8 and heat\$3 and pressure and	USPAT	
		mechan\$4 and (layer film wafer substrate))		12:25
		and (planar\$8 same heat\$3)) and (planar\$8		
		same (layer film wafer substrate))		0000/00/47
9	1288	(((planar\$8 and heat\$3 and pressure and	USPAT	2002/06/17
		mechan\$4 and (layer film wafer substrate))		12:28
		and (planar\$8 same heat\$3)) and (planar\$8		
		same (layer film wafer substrate))) and		1
		(planar\$8 same mechan\$4)		
10	58	planar\$8 and heat\$3 and pressure and	EPO; JPO;	2002/06/17
		mechan\$4 and (layer film wafer substrate)	DERWENT;	12:27
			IBM_TDB	
11	2248	planar\$8 and heat\$3 and pressure and	US-PGPUB	2002/06/17
		mechan\$4 and (layer film wafer substrate)		12:27
13	467		US-PGPUB	2002/06/17
	1	mechan\$4 and (layer film wafer substrate))		12:27
		and (planar\$8 same heat\$3)		
	727	the state of the s	USPAT	2002/06/17
	121	mechan\$4 and (layer film wafer substrate))		12:29
		and (planar\$8 same heat\$3)) and (planar\$8		
		same (layer film wafer substrate))) and		
		(planar\$8 same mechan\$4)) and (planar\$8		
		same pressure)		